

## IGBT

High speed 5 FAST IGBT in TRENCHSTOP™ 5 technology

## IGW40N65H5A

650V IGBT  
High speed switching series fifth generation

Data sheet

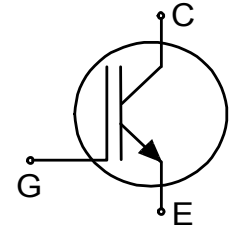
Industrial Power Control

### High speed 5 FAST IGBT in TRENCHSTOP™ 5 technology

#### Features and Benefits:

High speed H5 technology offering

- Best-in-Class efficiency in hard switching and resonant topologies
- Plug and play replacement of previous generation IGBTs
- 650V breakdown voltage
- Low gate charge  $Q_G$
- Maximum junction temperature 175°C
- Qualified according to AEC-Q101
- Green package (RoHS compliant)
- Complete product spectrum and PSpice Models:  
<http://www.infineon.com/igbt/>



#### Applications:

- Battery charger
- DC/DC converter

#### Package pin definition:

- Pin 1 - gate
- Pin 2 & backside - collector
- Pin 3 - emitter



#### Key Performance and Package Parameters

| Type        | $V_{CE}$ | $I_C$ | $V_{CEsat}, T_{vj}=25^\circ C$ | $T_{vjmax}$ | Marking | Package    |
|-------------|----------|-------|--------------------------------|-------------|---------|------------|
| IGW40N65H5A | 650V     | 40A   | 1.66V                          | 175°C       | G40EH5A | PG-TO247-3 |



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**Maximum Ratings**

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

| Parameter   | Symbol      | Value                | Unit               |
|---|-------------|----------------------|--------------------|
| Collector-emitter voltage, $T_{vj} \geq 25^{\circ}\text{C}$   | $V_{CE}$    | 650                  | V                  |
| DC collector current, limited by $T_{vjmax}$<br>$T_C = 25^{\circ}\text{C}$<br>$T_C = 100^{\circ}\text{C}$                 | $I_C$       | 74.0<br>46.0         | A                  |
| Pulsed collector current, $t_p$ limited by $T_{vjmax}^{1)}$   | $I_{Cpuls}$ | 120.0                | A                  |
| Turn off safe operating area<br>$V_{CE} \leq 650\text{V}$ , $T_{vj} \leq 175^{\circ}\text{C}$ , $t_p = 1\mu\text{s}^{1)}$ | -           | 120.0                | A                  |
| Gate-emitter voltage<br>Transient Gate-emitter voltage ( $t_p \leq 10\mu\text{s}$ , $D < 0.010$ )                         | $V_{GE}$    | $\pm 20$<br>$\pm 30$ | V                  |
| Power dissipation $T_C = 25^{\circ}\text{C}$<br>Power dissipation $T_C = 100^{\circ}\text{C}$                             | $P_{tot}$   | 250.0<br>125.0       | W                  |
| Operating junction temperature  | $T_{vj}$    | -40...+175           | $^{\circ}\text{C}$ |
| Storage temperature   | $T_{stg}$   | -55...+150           | $^{\circ}\text{C}$ |
| Soldering temperature, <sup>2)</sup><br>wave soldering 1.6mm (0.063in.) from case for 10s                                 |             | 260                  | $^{\circ}\text{C}$ |
| Mounting torque, M3 screw<br>Maximum of mounting processes: 3   | $M$         | 0.6                  | Nm                 |

**Thermal Resistance**

| Parameter                                | Symbol        | Conditions | Max. Value | Unit |
|--|---------------|------------|------------|------|
| <b>Characteristic</b>                    |               |            |            |      |
| IGBT thermal resistance, junction - case | $R_{th(j-c)}$ |            | 0.60       | K/W  |
| Thermal resistance junction - ambient    | $R_{th(j-a)}$ |            | 40         | K/W  |

**Electrical Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$ , unless otherwise specified**

| Parameter                            | Symbol        | Conditions  | Value       |                      |                | Unit          |
|--------------------------------------|---------------|---|-------------|----------------------|----------------|---------------|
|                                      |               |   | min.        | typ.                 | max.           |               |
| <b>Static Characteristic</b>         |               |   |             |                      |                |               |
| Collector-emitter breakdown voltage  | $V_{(BR)CES}$ | $V_{GE} = 0\text{V}$ , $I_C = 0.20\text{mA}$  | 650         | -                    | -              | V             |
| Collector-emitter saturation voltage | $V_{CEsat}$   | $V_{GE} = 15.0\text{V}$ , $I_C = 40.0\text{A}$<br>$T_{vj} = 25^{\circ}\text{C}$<br>$T_{vj} = 125^{\circ}\text{C}$<br>$T_{vj} = 175^{\circ}\text{C}$ | -<br>-<br>- | 1.66<br>1.85<br>2.05 | 2.10<br>-<br>- | V             |
| Gate-emitter threshold voltage       | $V_{GE(th)}$  | $I_C = 0.40\text{mA}$ , $V_{CE} = V_{GE}$   | 3.2         | 4.0                  | 4.8            | V             |
| Zero gate voltage collector current  | $I_{CES}$     | $V_{CE} = 650\text{V}$ , $V_{GE} = 0\text{V}$<br>$T_{vj} = 25^{\circ}\text{C}$<br>$T_{vj} = 175^{\circ}\text{C}$                                    | -<br>-      | -<br>500.0           | 40.0<br>-      | $\mu\text{A}$ |
| Gate-emitter leakage current         | $I_{GES}$     | $V_{CE} = 0\text{V}$ , $V_{GE} = 20\text{V}$  | -           | -                    | 100            | nA            |
| Transconductance                     | $g_{fs}$      | $V_{CE} = 20\text{V}$ , $I_C = 40.0\text{A}$  | -           | 50.0                 | -              | S             |

<sup>1)</sup> Defined by design. Not subject to production test.

<sup>2)</sup> Package not recommended for surface mount applications

**Electrical Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$ , unless otherwise specified**

| Parameter  | Symbol    | Conditions  | Value |      |      | Unit |
|--|-----------|---|-------|------|------|------|
|  |           |   | min.  | typ. | max. |      |
| <b>Dynamic Characteristic</b>                                  |           |   |       |      |      |      |
| Input capacitance  | $C_{ies}$ | $V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$      | -     | 2300 | -    | pF   |
| Output capacitance   | $C_{oes}$ |   | -     | 43   | -    |      |
| Reverse transfer capacitance                                   | $C_{res}$ |   | -     | 9    | -    |      |
| Gate charge  | $Q_G$     | $V_{CC} = 520\text{V}, I_C = 40.0\text{A}, V_{GE} = 15\text{V}$ | -     | 92.0 | -    | nC   |
| Internal emitter inductance measured 5mm (0.197 in.) from case | $L_E$     |   | -     | 13.0 | -    | nH   |

**Switching Characteristic, Inductive Load**

| Parameter | Symbol | Conditions | Value |      |      | Unit |
|-----------|--------|------------|-------|------|------|------|
|           |        |            | min.  | typ. | max. |      |

**IGBT Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$** 

|                        |              |   |   |      |   |    |
|------------------------|--------------|---|---|------|---|----|
| Turn-on delay time     | $t_{d(on)}$  | $T_{vj} = 25^{\circ}\text{C}, V_{CC} = 400\text{V}, I_C = 20.0\text{A}, V_{GE} = 0.0/15.0\text{V}, R_{G(on)} = 15.0\Omega, R_{G(off)} = 15.0\Omega, L\sigma = 30\text{nH}, C\sigma = 30\text{pF}$<br>Energy losses include "tail" and diode reverse recovery. | - | 20   | - | ns |
| Rise time              | $t_r$        |   | - | 11   | - | ns |
| Turn-off delay time    | $t_{d(off)}$ |   | - | 149  | - | ns |
| Fall time              | $t_f$        |   | - | 11   | - | ns |
| Turn-on energy         | $E_{on}$     |   | - | 0.36 | - | mJ |
| Turn-off energy        | $E_{off}$    |   | - | 0.11 | - | mJ |
| Total switching energy | $E_{ts}$     |   | - | 0.47 | - | mJ |
| Turn-on delay time     | $t_{d(on)}$  | $T_{vj} = 25^{\circ}\text{C}, V_{CC} = 400\text{V}, I_C = 5.0\text{A}, V_{GE} = 0.0/15.0\text{V}, R_{G(on)} = 15.0\Omega, R_{G(off)} = 15.0\Omega, L\sigma = 30\text{nH}, C\sigma = 30\text{pF}$<br>Energy losses include "tail" and diode reverse recovery.  | - | 18   | - | ns |
| Rise time              | $t_r$        |   | - | 4    | - | ns |
| Turn-off delay time    | $t_{d(off)}$ |   | - | 156  | - | ns |
| Fall time              | $t_f$        |   | - | 24   | - | ns |
| Turn-on energy         | $E_{on}$     |   | - | 0.08 | - | mJ |
| Turn-off energy        | $E_{off}$    |   | - | 0.03 | - | mJ |
| Total switching energy | $E_{ts}$     |   | - | 0.11 | - | mJ |

**Switching Characteristic, Inductive Load**

| Parameter  | Symbol       | Conditions   | Value |      |      | Unit |
|--|--------------|--|-------|------|------|------|
|  |              |  | min.  | typ. | max. |      |
| <b>IGBT Characteristic, at <math>T_{vj} = 150^{\circ}\text{C}</math></b> |              |  |       |      |      |      |
| Turn-on delay time   | $t_{d(on)}$  | $T_{vj} = 150^{\circ}\text{C}$ ,<br>$V_{CC} = 400\text{V}$ , $I_C = 20.0\text{A}$ ,<br>$V_{GE} = 0.0/15.0\text{V}$ ,<br>$R_{G(on)} = 15.0\Omega$ , $R_{G(off)} = 15.0\Omega$ ,<br>$L\sigma = 30\text{nH}$ , $C\sigma = 30\text{pF}$<br>$L\sigma$ , $C\sigma$ from Fig. E<br>Energy losses include "tail" and diode reverse recovery. | -     | 19   | -    | ns   |
| Rise time  | $t_r$        |  | -     | 12   | -    | ns   |
| Turn-off delay time  | $t_{d(off)}$ |  | -     | 186  | -    | ns   |
| Fall time  | $t_f$        |  | -     | 17   | -    | ns   |
| Turn-on energy   | $E_{on}$     |  | -     | 0.55 | -    | mJ   |
| Turn-off energy  | $E_{off}$    |  | -     | 0.22 | -    | mJ   |
| Total switching energy   | $E_{ts}$     |  | -     | 0.77 | -    | mJ   |
| Turn-on delay time   | $t_{d(on)}$  | $T_{vj} = 150^{\circ}\text{C}$ ,<br>$V_{CC} = 400\text{V}$ , $I_C = 5.0\text{A}$ ,<br>$V_{GE} = 0.0/15.0\text{V}$ ,<br>$R_{G(on)} = 15.0\Omega$ , $R_{G(off)} = 15.0\Omega$ ,<br>$L\sigma = 30\text{nH}$ , $C\sigma = 30\text{pF}$<br>$L\sigma$ , $C\sigma$ from Fig. E<br>Energy losses include "tail" and diode reverse recovery.  | -     | 17   | -    | ns   |
| Rise time  | $t_r$        |  | -     | 5    | -    | ns   |
| Turn-off delay time  | $t_{d(off)}$ |  | -     | 212  | -    | ns   |
| Fall time  | $t_f$        |  | -     | 36   | -    | ns   |
| Turn-on energy   | $E_{on}$     |  | -     | 0.16 | -    | mJ   |
| Turn-off energy  | $E_{off}$    |  | -     | 0.07 | -    | mJ   |
| Total switching energy   | $E_{ts}$     |  | -     | 0.23 | -    | mJ   |

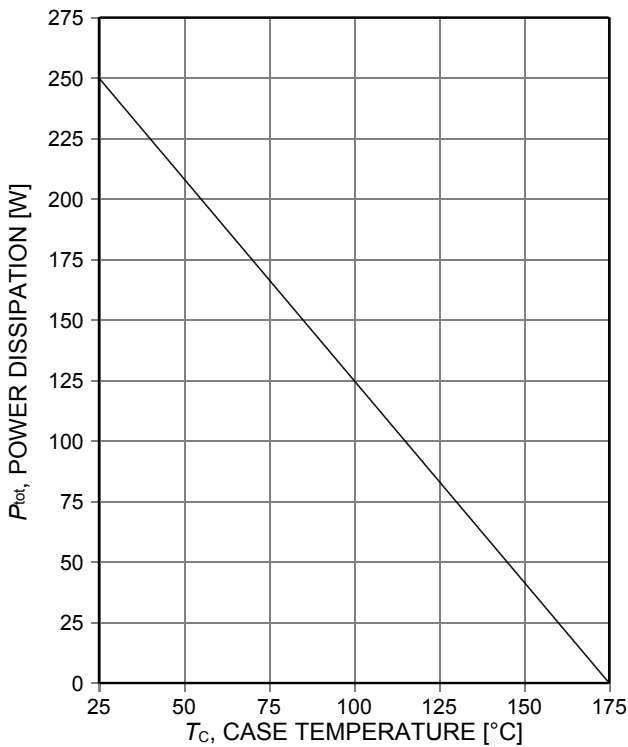


Figure 1. Power dissipation as a function of case temperature ( $T_{vj} \leq 175^\circ\text{C}$ )

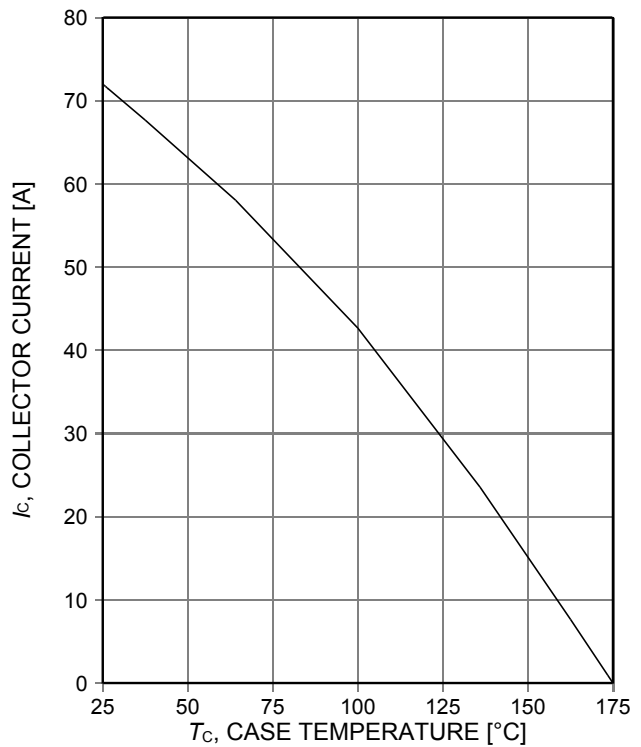


Figure 2. Collector current as a function of case temperature ( $V_{GE} \geq 15\text{V}$ ,  $T_{vj} \leq 175^\circ\text{C}$ )

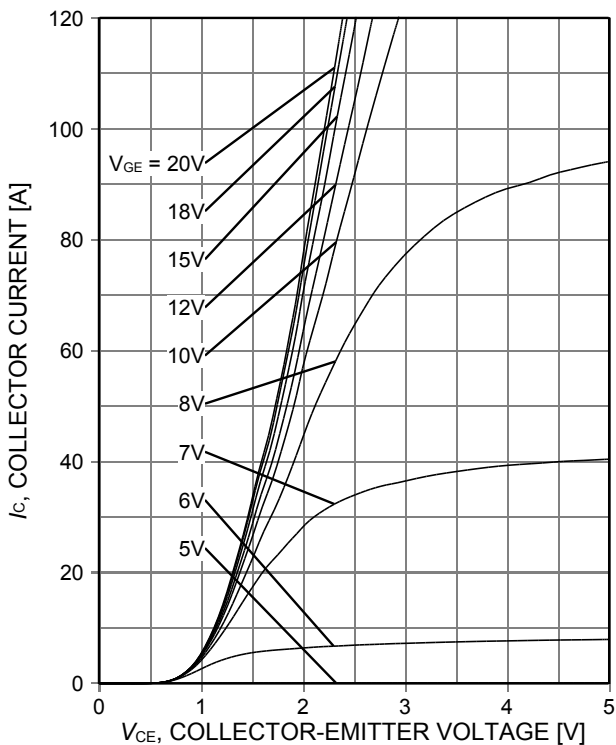


Figure 3. Typical output characteristic ( $T_{vj} = 25^\circ\text{C}$ )

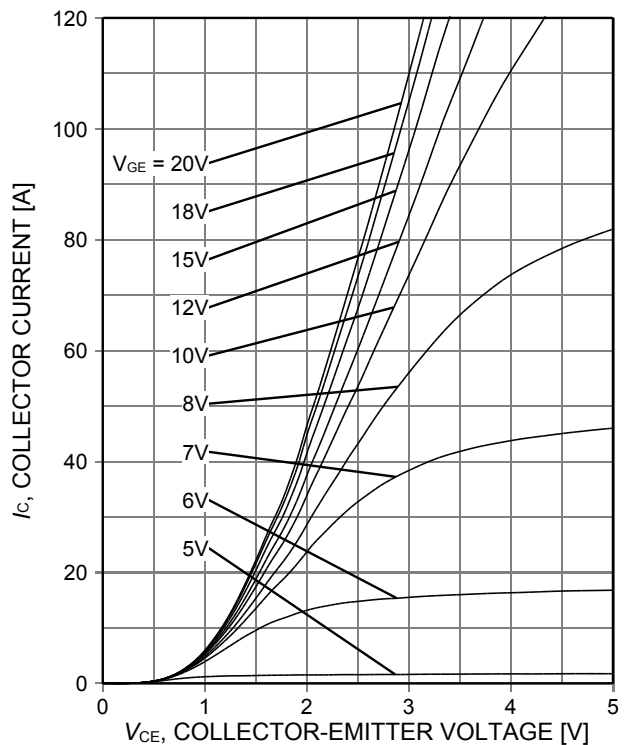


Figure 4. Typical output characteristic ( $T_{vj} = 150^\circ\text{C}$ )

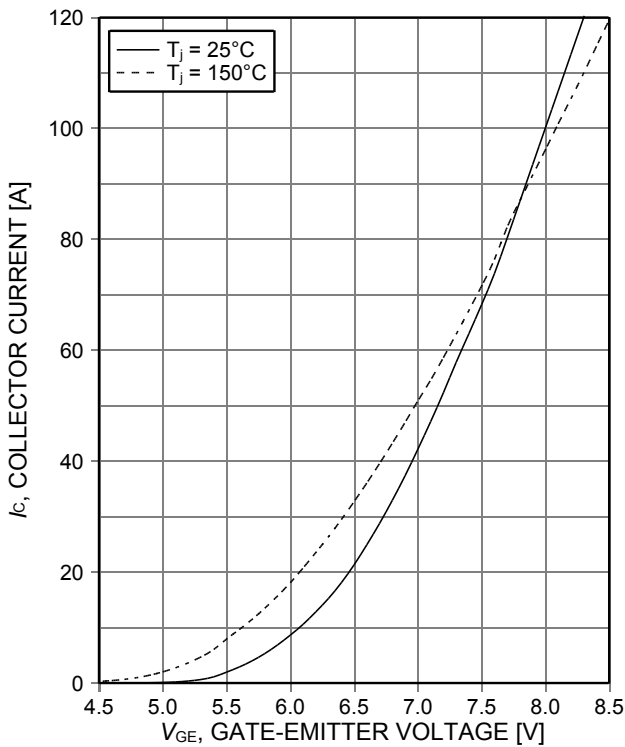


Figure 5. **Typical transfer characteristic**  
( $V_{CE}=20V$ )

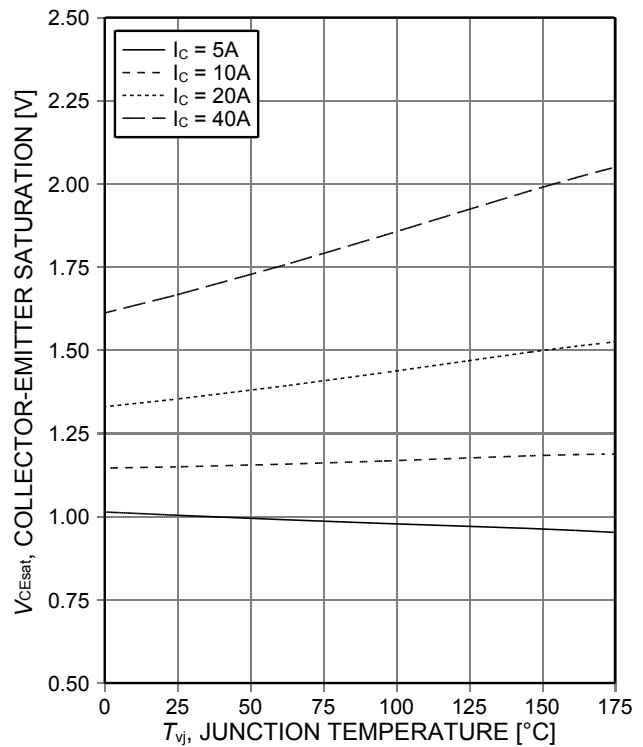


Figure 6. **Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE}=15V$ )

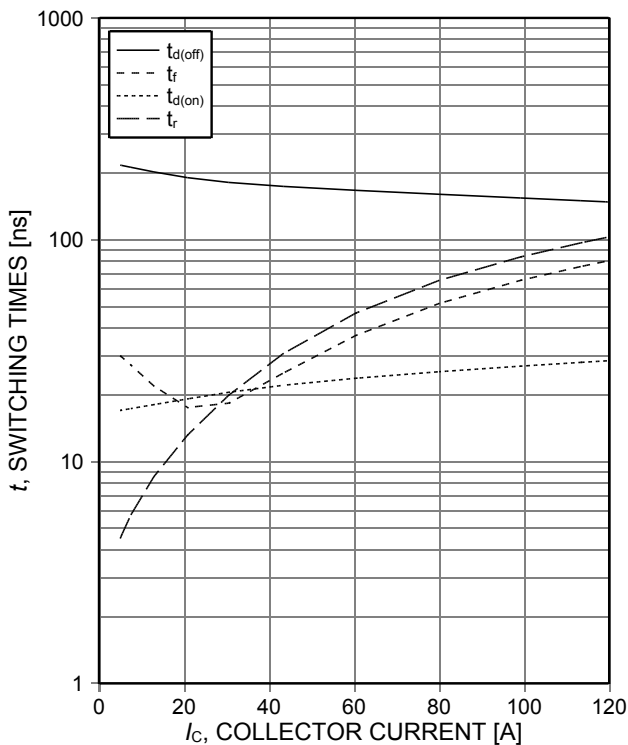


Figure 7. **Typical switching times as a function of collector current**  
(inductive load,  $T_{vj}=150^{\circ}C$ ,  $V_{CE}=400V$ ,  $V_{GE}=15/0V$ ,  $r_G=15\Omega$ , Dynamic test circuit in Figure E)

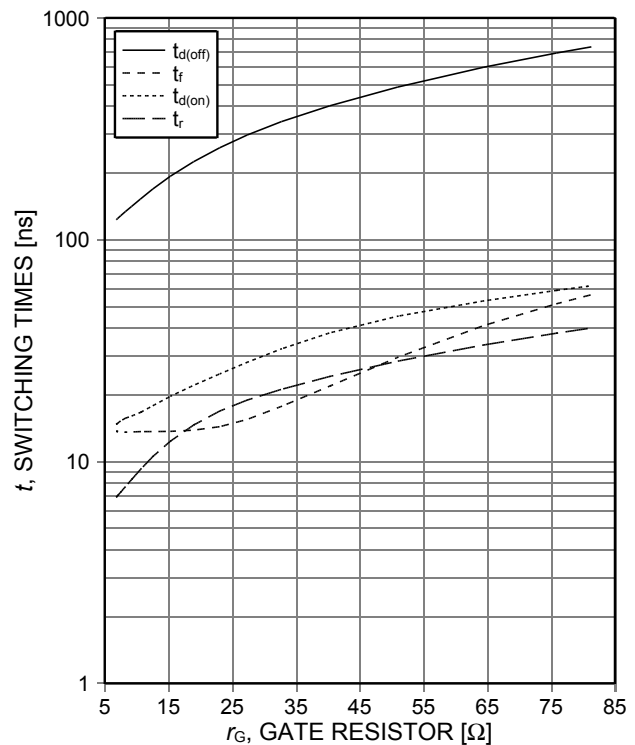


Figure 8. **Typical switching times as a function of gate resistor**  
(inductive load,  $T_{vj}=150^{\circ}C$ ,  $V_{CE}=400V$ ,  $V_{GE}=15/0V$ ,  $I_C=20A$ , Dynamic test circuit in Figure E)



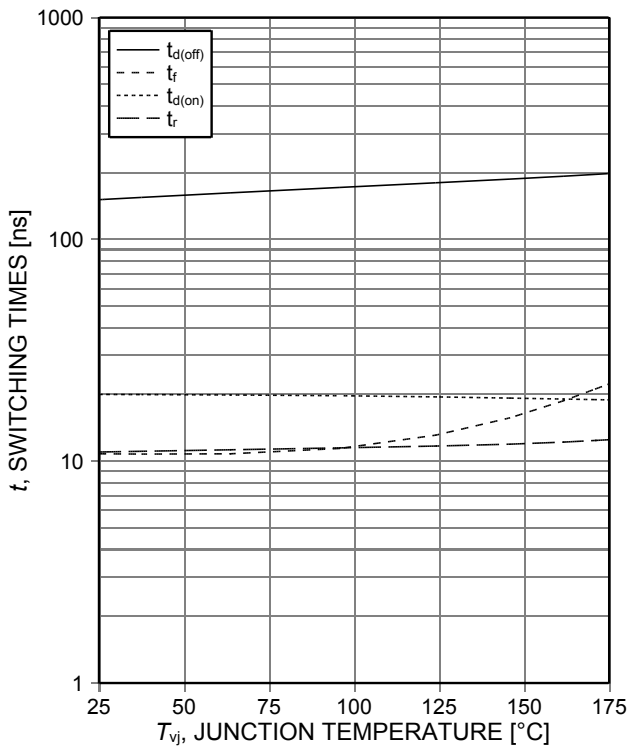


Figure 9. **Typical switching times as a function of junction temperature**  
 (inductive load,  $V_{CE}=400V$ ,  $V_{GE}=15/0V$ ,  $I_C=20A$ ,  $r_G=15\Omega$ , Dynamic test circuit in Figure E)

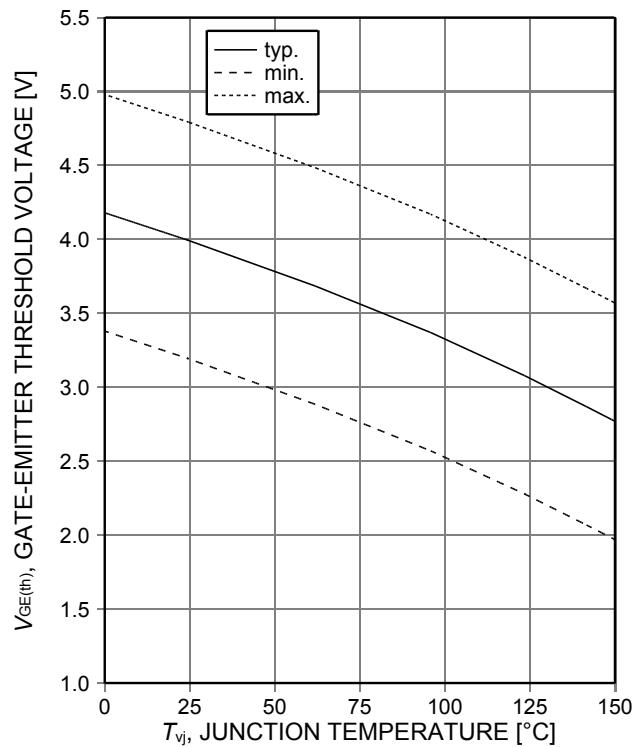


Figure 10. **Gate-emitter threshold voltage as a function of junction temperature**  
 ( $I_C=0.4mA$ )

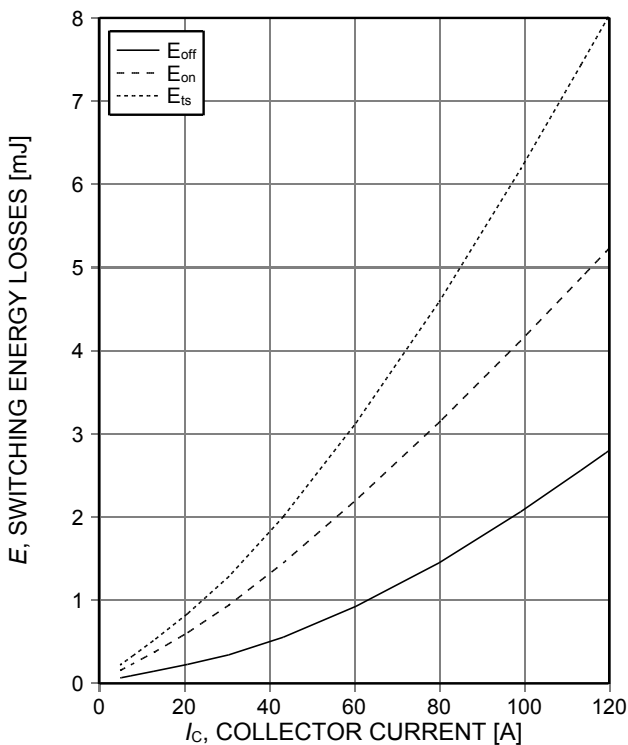


Figure 11. **Typical switching energy losses as a function of collector current**  
 (inductive load,  $T_{vj}=150^\circ C$ ,  $V_{CE}=400V$ ,  $V_{GE}=15/0V$ ,  $r_G=15\Omega$ , Dynamic test circuit in Figure E)

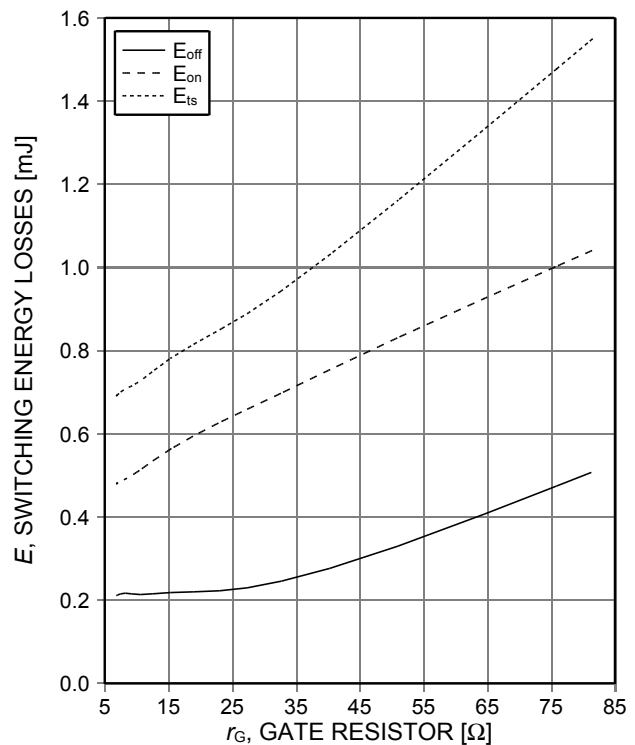


Figure 12. **Typical switching energy losses as a function of gate resistor**  
 (inductive load,  $T_{vj}=150^\circ C$ ,  $V_{CE}=400V$ ,  $V_{GE}=15/0V$ ,  $I_C=20A$ , Dynamic test circuit in Figure E)

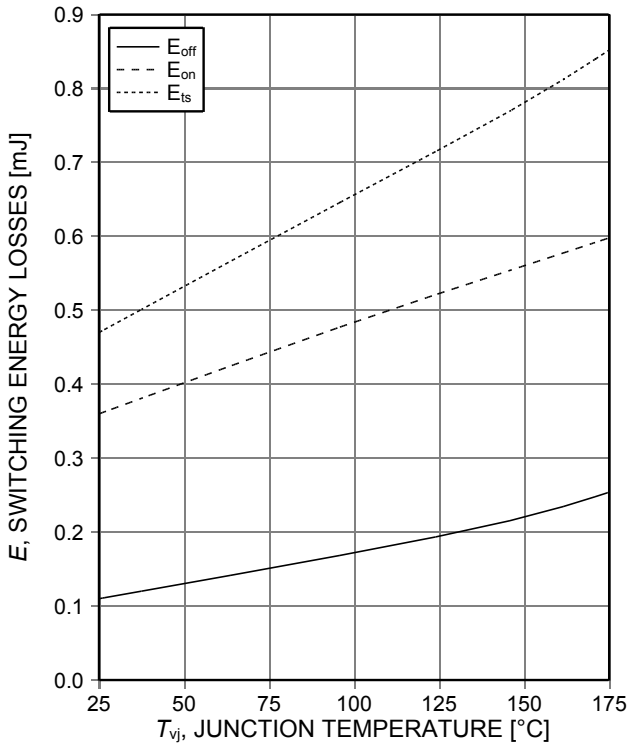


Figure 13. **Typical switching energy losses as a function of junction temperature**  
(inductive load,  $V_{CE}=400V$ ,  $V_{GE}=15/0V$ ,  $I_C=20A$ ,  $r_G=15\Omega$ , Dynamic test circuit in Figure E)

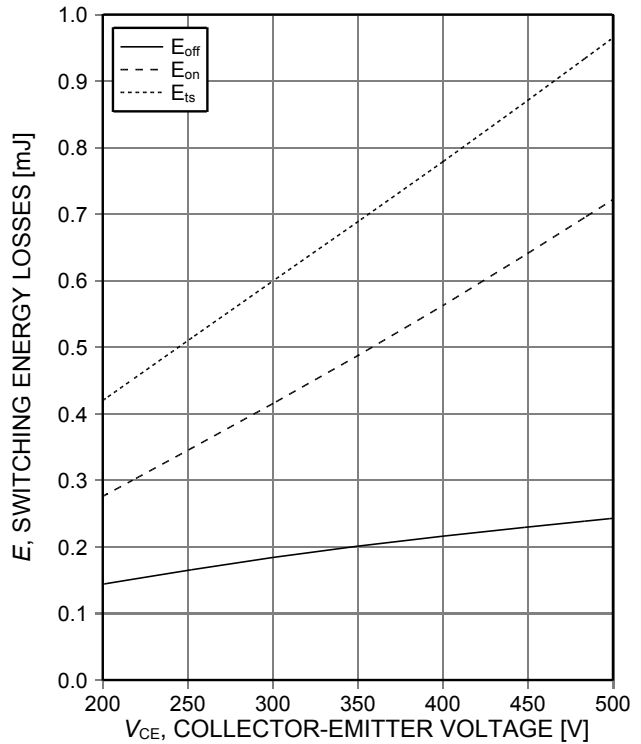


Figure 14. **Typical switching energy losses as a function of collector emitter voltage**  
(inductive load,  $T_{vj}=150^\circ C$ ,  $V_{GE}=15/0V$ ,  $I_C=20A$ ,  $r_G=15\Omega$ , Dynamic test circuit in Figure E)

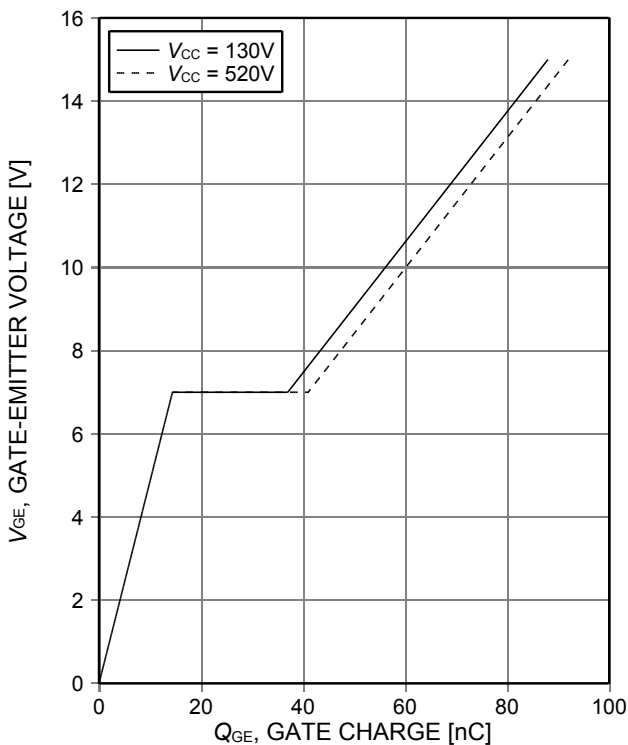


Figure 15. **Typical gate charge**  
( $I_C=40A$ )

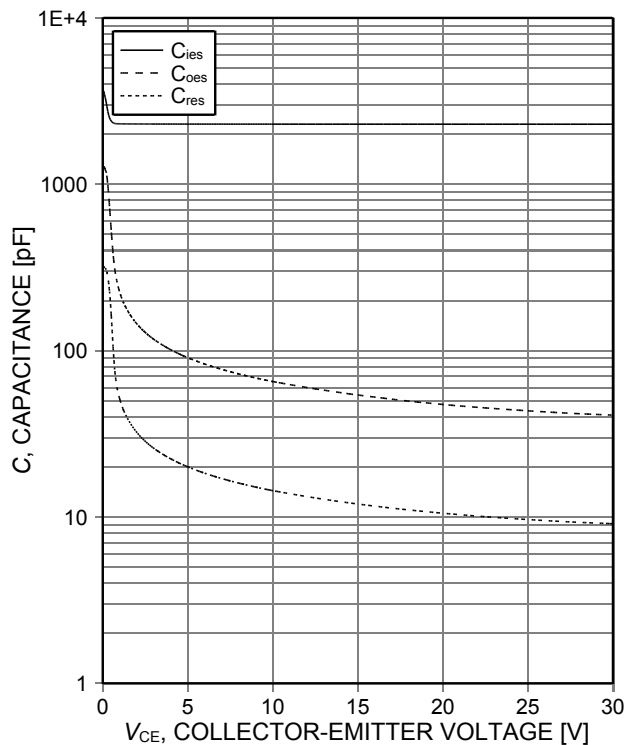


Figure 16. **Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE}=0V$ ,  $f=1MHz$ )

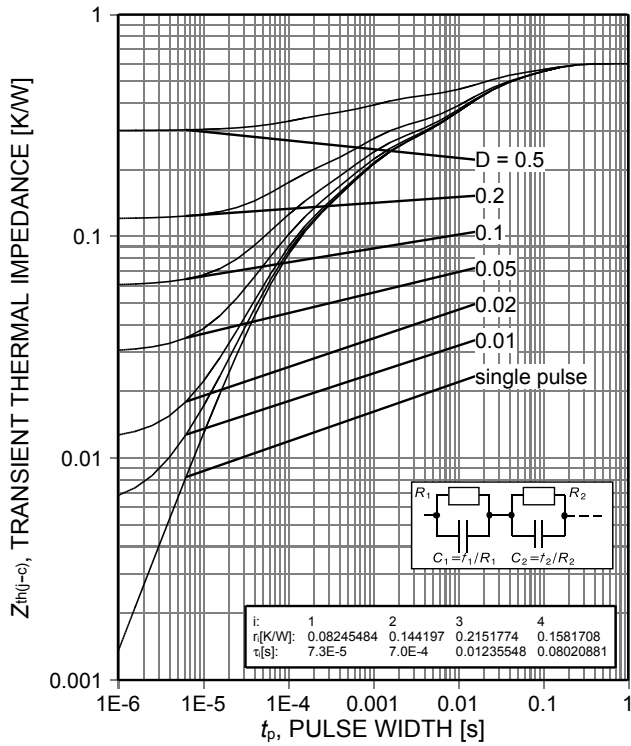
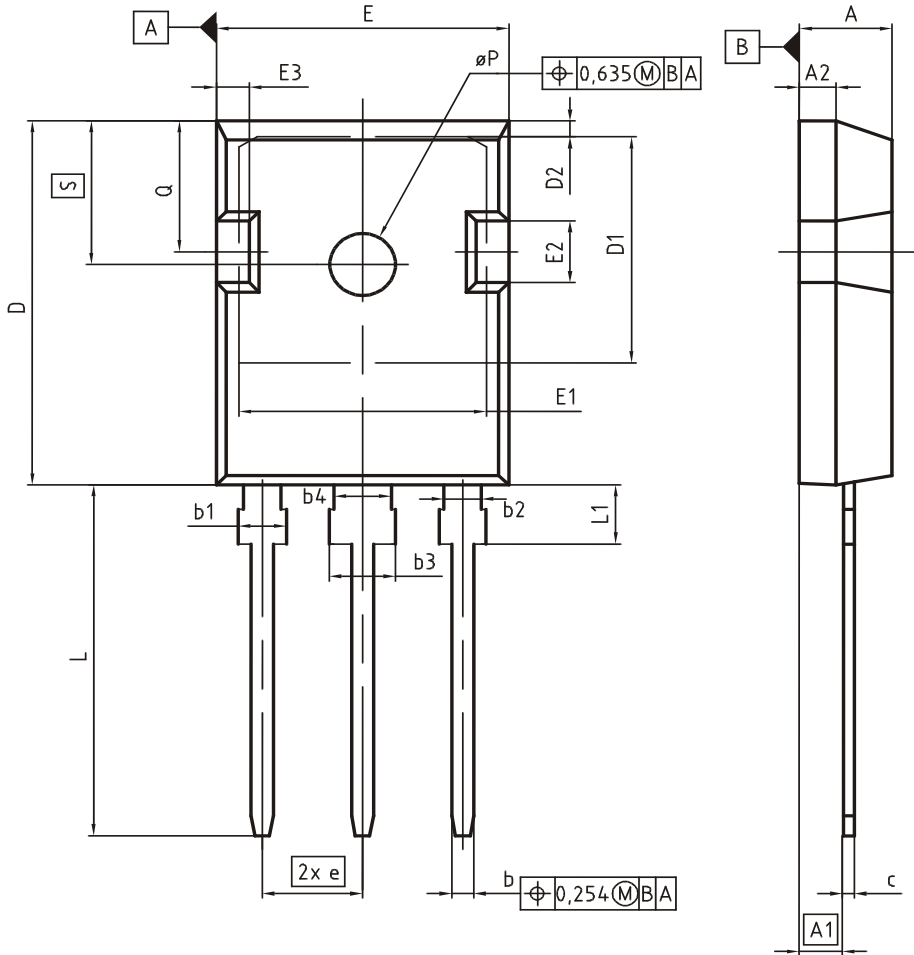


Figure 17. IGBT transient thermal impedance ( $D=t_p/T$ )

PG-TO247-3



| DIM | MILLIMETERS |       | INCHES      |       |
|-----|-------------|-------|-------------|-------|
|     | MIN         | MAX   | MIN         | MAX   |
| A   | 4.83        | 5.21  | 0.190       | 0.205 |
| A1  | 2.27        | 2.54  | 0.089       | 0.100 |
| A2  | 1.85        | 2.16  | 0.073       | 0.085 |
| b   | 1.07        | 1.33  | 0.042       | 0.052 |
| b1  | 1.90        | 2.41  | 0.075       | 0.095 |
| b2  | 1.90        | 2.16  | 0.075       | 0.085 |
| b3  | 2.87        | 3.38  | 0.113       | 0.133 |
| b4  | 2.87        | 3.13  | 0.113       | 0.123 |
| c   | 0.55        | 0.68  | 0.022       | 0.027 |
| D   | 20.80       | 21.10 | 0.819       | 0.831 |
| D1  | 16.25       | 17.65 | 0.640       | 0.695 |
| D2  | 0.95        | 1.35  | 0.037       | 0.053 |
| E   | 15.70       | 16.13 | 0.618       | 0.635 |
| E1  | 13.10       | 14.15 | 0.516       | 0.557 |
| E2  | 3.68        | 5.10  | 0.145       | 0.201 |
| E3  | 1.00        | 2.60  | 0.039       | 0.102 |
| e   | 5.44 (BSC)  |       | 0.214 (BSC) |       |
| N   | 3           |       | 3           |       |
| L   | 19.80       | 20.32 | 0.780       | 0.800 |
| L1  | 4.10        | 4.47  | 0.161       | 0.176 |
| øP  | 3.50        | 3.70  | 0.138       | 0.146 |
| Q   | 5.49        | 6.00  | 0.216       | 0.236 |
| S   | 6.04        | 6.30  | 0.238       | 0.248 |

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Z8B00003327

SCALE

EUROPEAN PROJECTION

ISSUE DATE  
09-07-2010

REVISION  
05

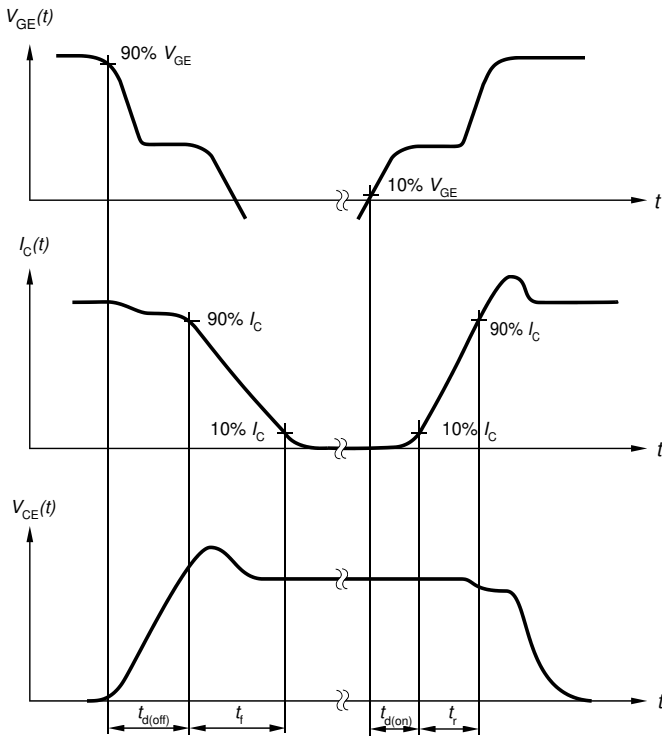


Figure A. Definition of switching times

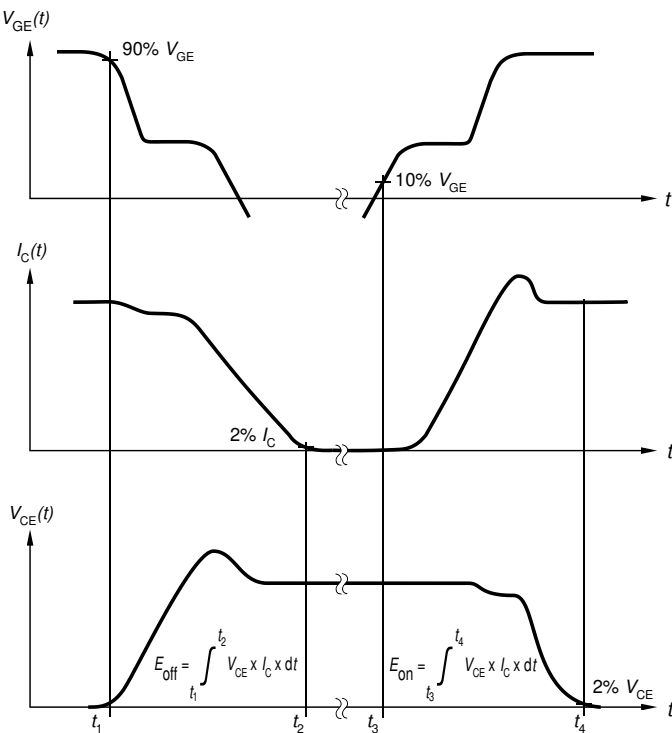


Figure B. Definition of switching losses

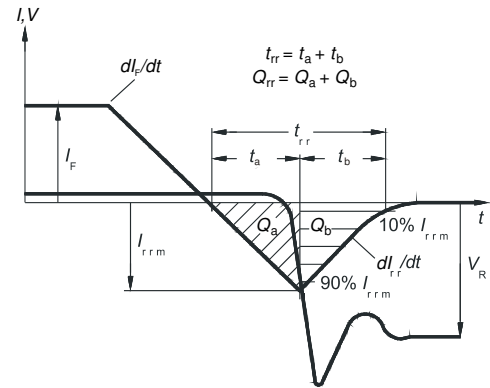


Figure C. Definition of diode switching characteristics

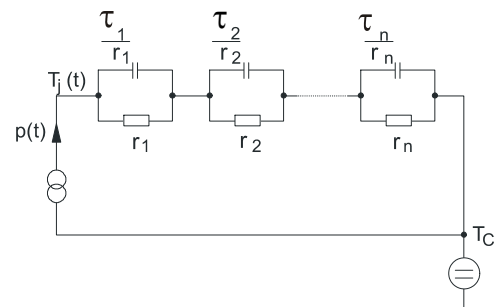


Figure D. Thermal equivalent circuit

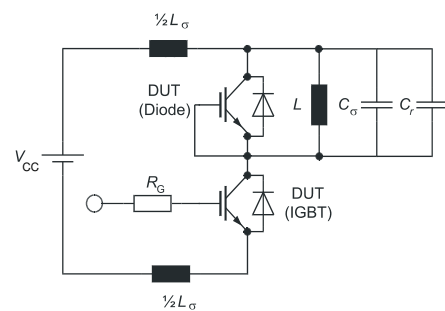


Figure E. Dynamic test circuit  
Parasitic inductance  $L_{\sigma}$ ,  
parasitic capacitor  $C_{\sigma}$ ,  
relief capacitor  $C_r$ ,  
(only for ZVT switching)

## Revision History

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IGW40N65H5A

Revision: 2014-12-15, Rev. 2.1

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Previous Revision

| Revision | Date       | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.1      | 2014-12-15 | Final data sheet                             |

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